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REVISIONS			
REV	DESCRIPTION	DATE	BY
A	ECO 2133835: INITIAL RELEASE	6/6/2013	BMH
B	ECO 2134093: CORRECT WINDOW THK TOL, ZONE B6	6/17/2013	BMH

NOTES UNLESS OTHERWISE SPECIFIED:

- 1 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY.
- 2 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND HAS A MAXIMUM ALLOWED VALUE OF 0.6 DEGREES.
- 3 BOUNDARY MIRRORS SURROUNDING THE DMD ACTIVE ARRAY.
- 4 NOTCH DIMENSIONS ARE DEFINED BY UPPERMOST LAYERS OF CERAMIC, AS SHOWN IN SECTION A-A.
- 5 ENCAPSULANT TO BE CONTAINED WITHIN DIMENSIONS SHOWN IN VIEW C (SHEET 2). NO ENCAPSULANT IS ALLOWED ON TOP OF THE WINDOW.
- 6 ENCAPSULANT NOT TO EXCEED THE HEIGHT OF THE WINDOW.
- 7 DATUM B IS DEFINED BY A DIA. 2.5 PIN, WITH A FLAT ON THE SIDE FACING TOWARD THE CENTER OF THE ACTIVE ARRAY, AS SHOWN IN VIEW B (SHEET 2).
- 8 WHILE ONLY THE THREE DATUM A TARGET AREAS A1, A2, AND A3 ARE USED FOR MEASUREMENT, ALL 4 CORNERS SHOULD BE CONTACTED, INCLUDING E1, TO SUPPORT MECHANICAL LOADS.

D

D

C

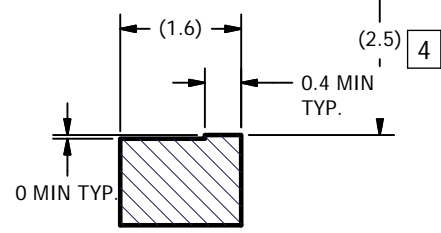
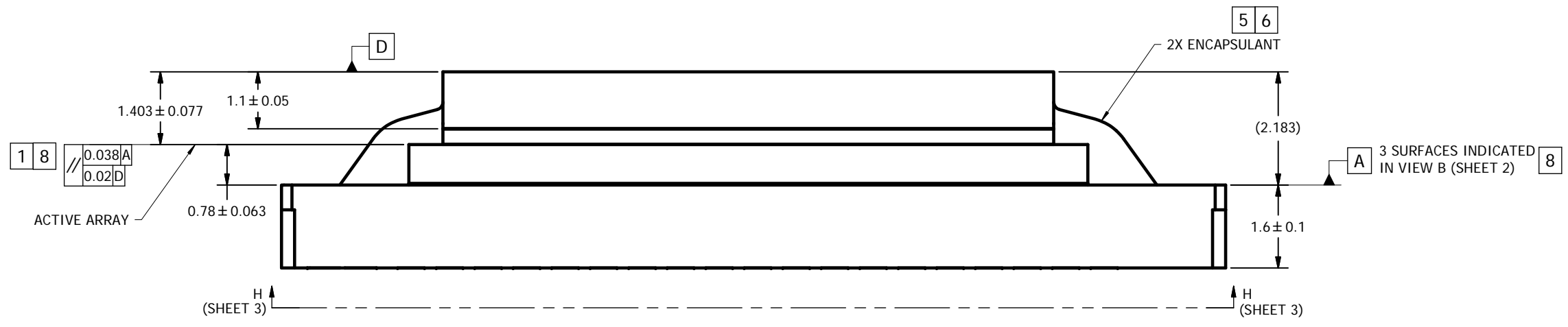
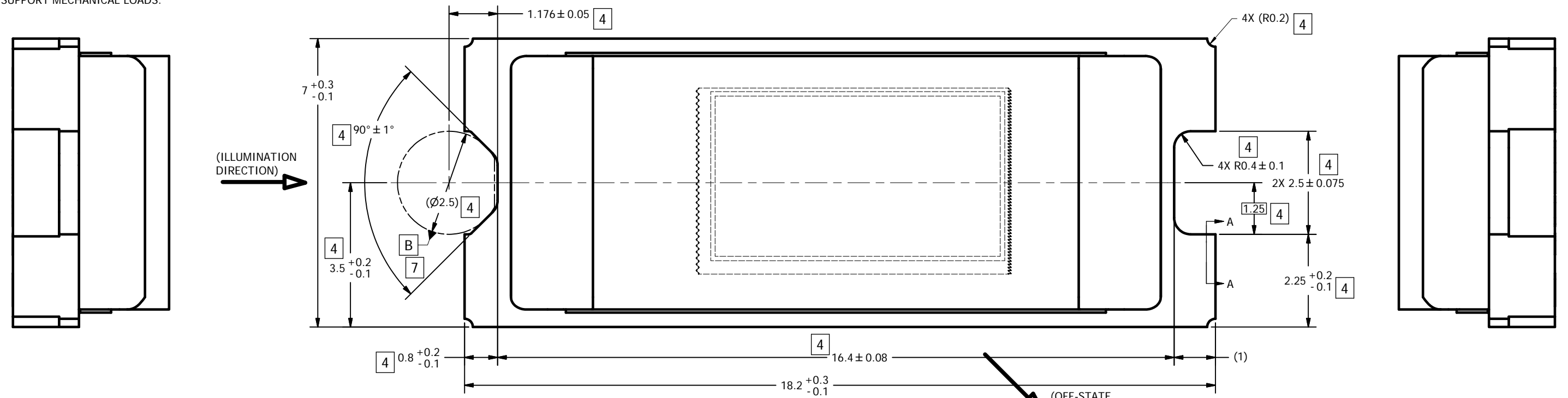
C

B

B

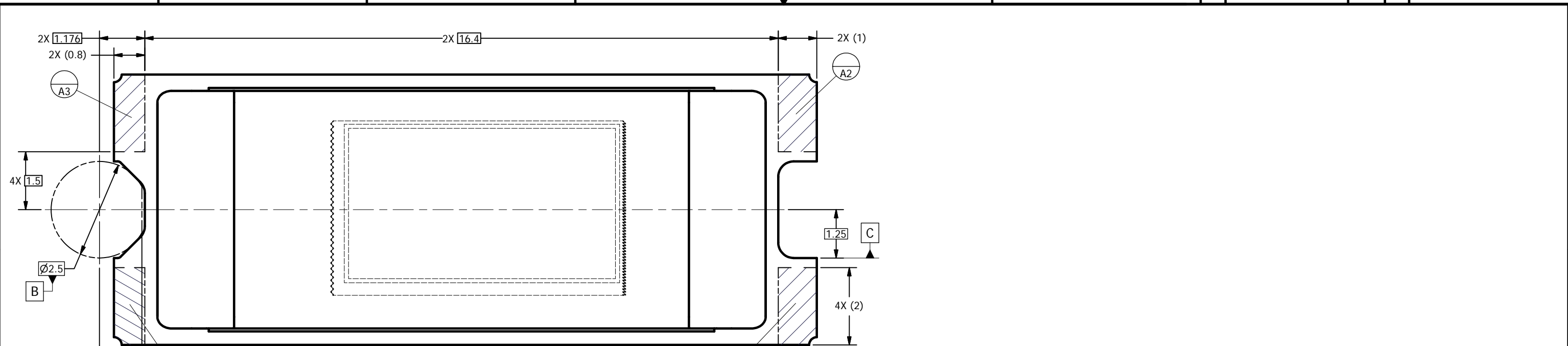
A

A

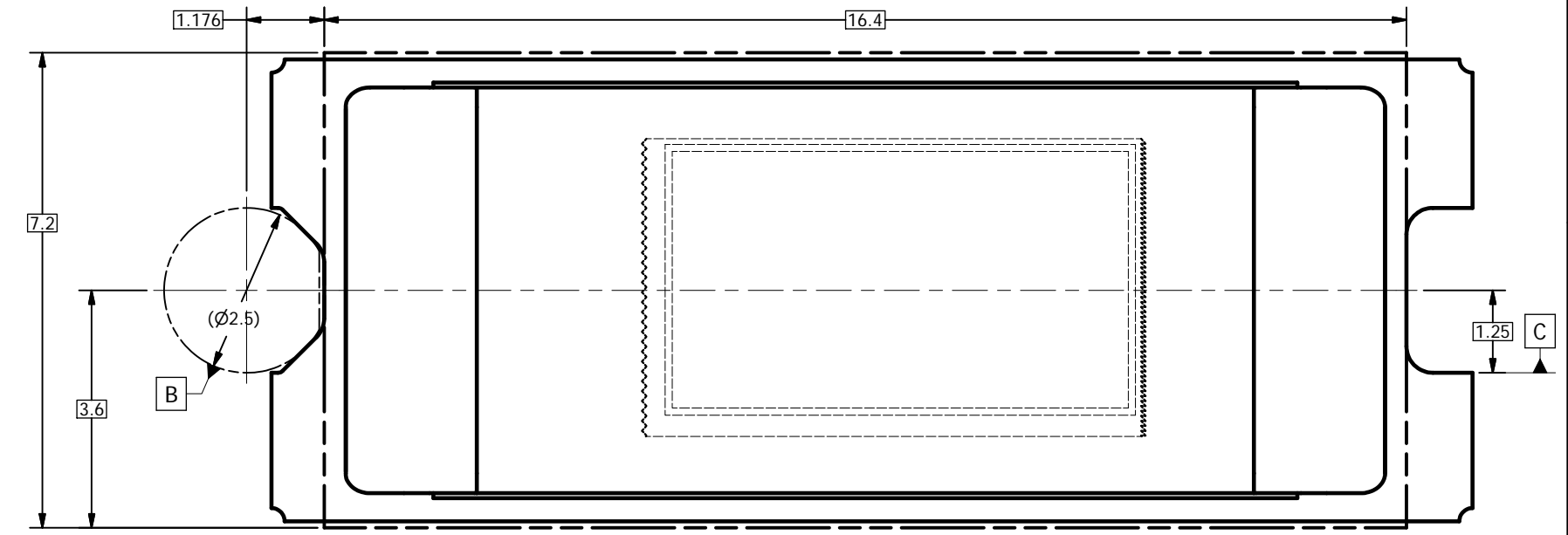


SECTION A-A
NOTCH OFFSETS

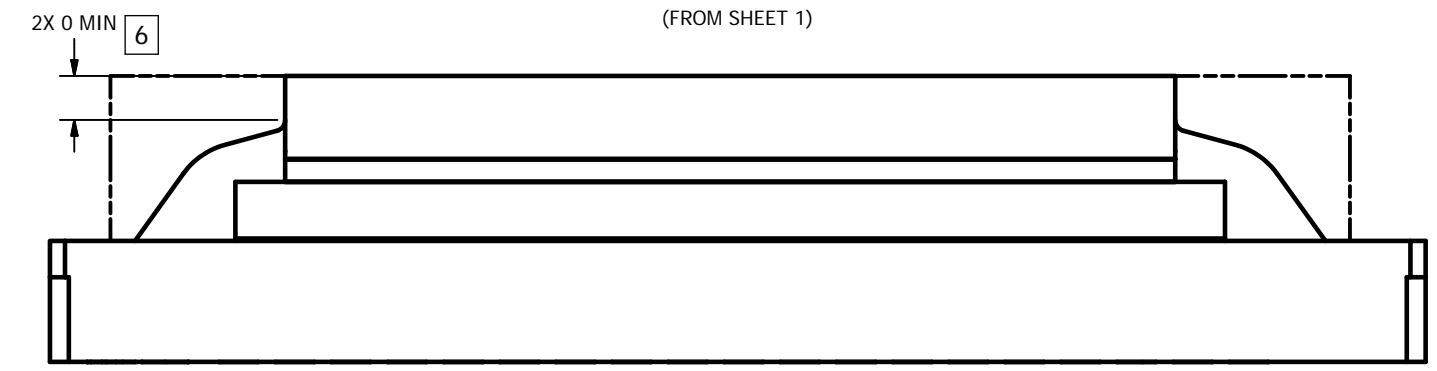
UNLESS OTHERWISE SPECIFIED		DRAWN B. HASKETT 6/6/2013		DATE 6/6/2013	
● DIMENSIONS ARE IN MILLIMETERS		ENGINEER B. HASKETT 6/6/2013		TITLE ICD, MECHANICAL, DMD, .3 720p SERIES 245	
● TOLERANCES:		QA/CE P. KONRAD 6/7/2013		SIZE D	
ANGLES ± 1°		CM S. SUSI 6/6/2013		DWG NO. 2512014	
2 PLACE DECIMALS ± 0.25		APPROVED S. CROFF 6/10/2013		REV B	
1 PLACE DECIMALS ± 0.50		R. LONG 6/6/2013		SCALE 20:1	
● DIMENSIONAL LIMITS APPLY BEFORE PROCEEDING		APPLICATION 0314DA NEXT ASSY USED ON		SHEET 1 OF 3	
● INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994					
● REMOVE ALL BURRS AND SHARP EDGES					
● PARENTHEetical INFORMATION FOR REFERENCE ONLY					



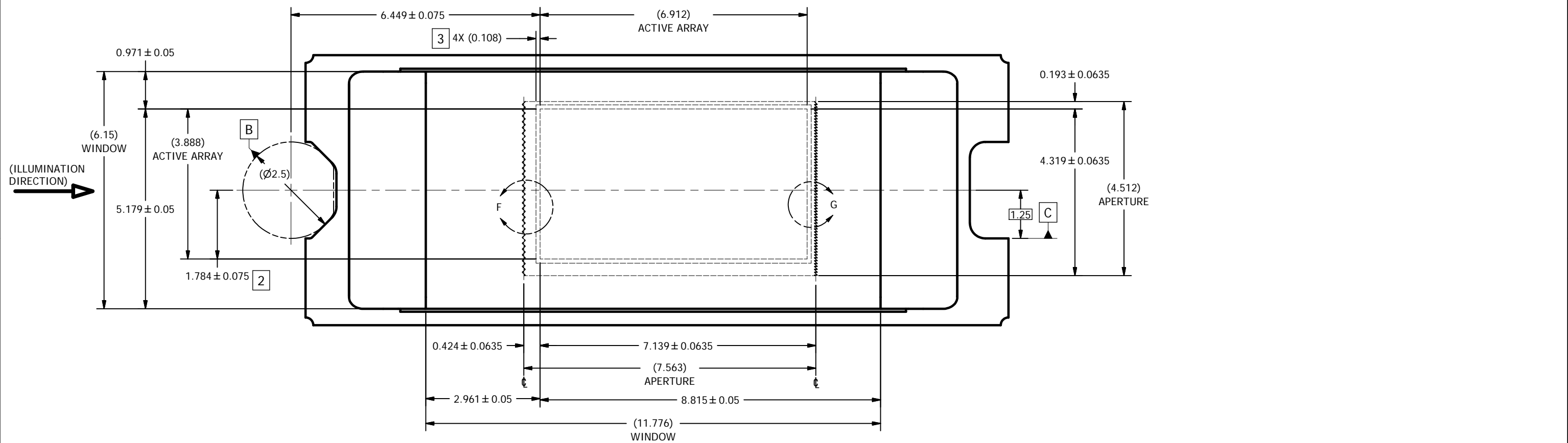
VIEW B
DATUMS A, B, C, AND E
(FROM SHEET 1)



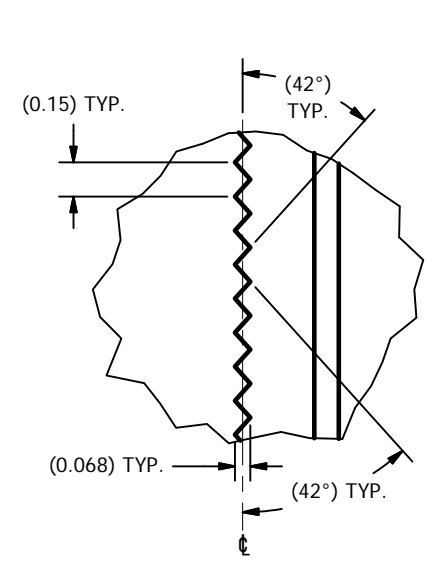
VIEW C 5
ENCAPSULANT MAXIMUM X/Y DIMENSIONS
(FROM SHEET 1)



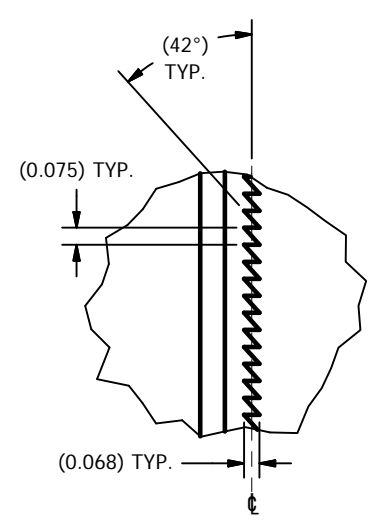
VIEW D
ENCAPSULANT MAXIMUM HEIGHT



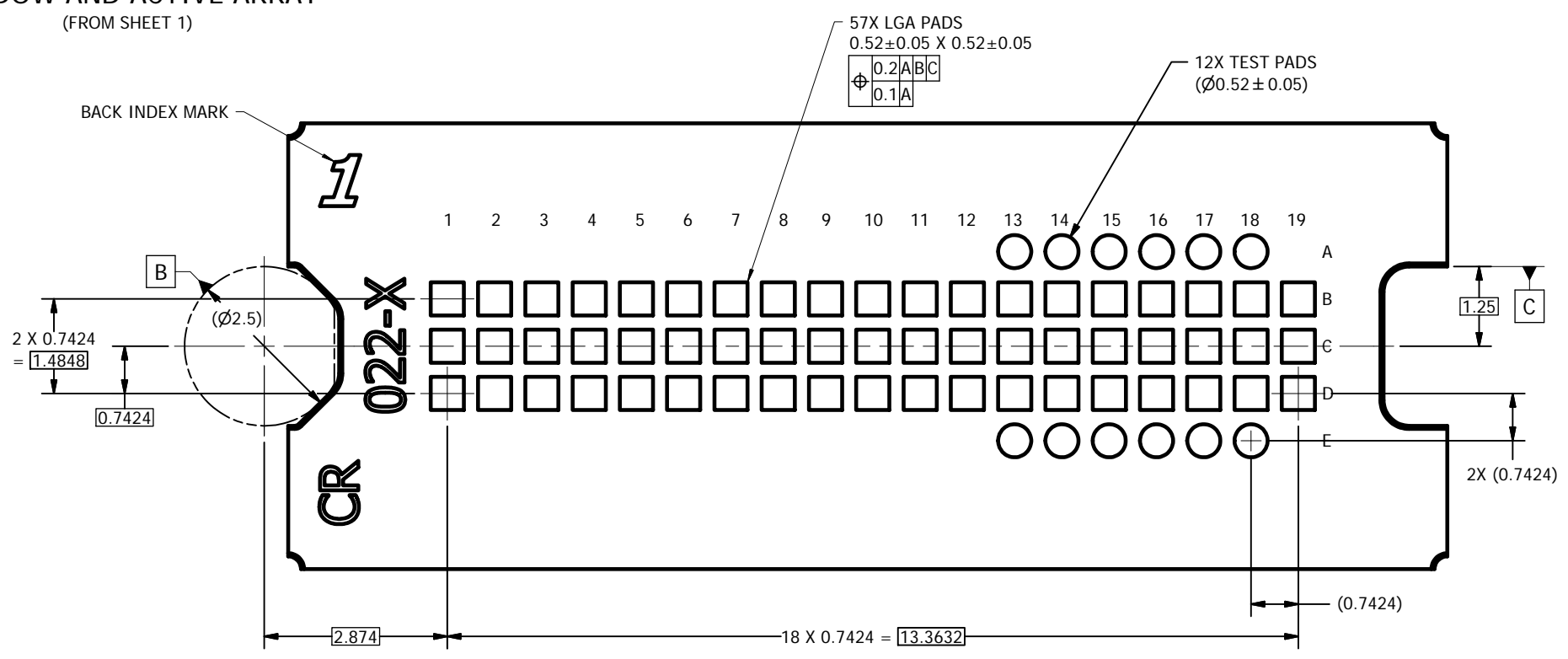
VIEW E
WINDOW AND ACTIVE ARRAY
(FROM SHEET 1)



DETAIL F
APERTURE LEFT EDGE
SCALE 60 : 1



DETAIL G
APERTURE RIGHT EDGE
SCALE 60 : 1



VIEW H-H
BACK SIDE METALLIZATION
(FROM SHEET 1)

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